

## Description

The TWS3H7 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic SSOP4 package with different lead forming options.

With the robust coplanar double mold structure, TWS3H7 series provide the most stable isolation feature.

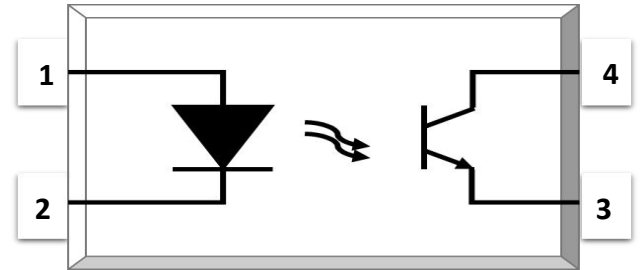
## Features

- High isolation 3750 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- REACH compliance
- Halogen free
- MSL class 1
- Regulatory Approvals

## Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

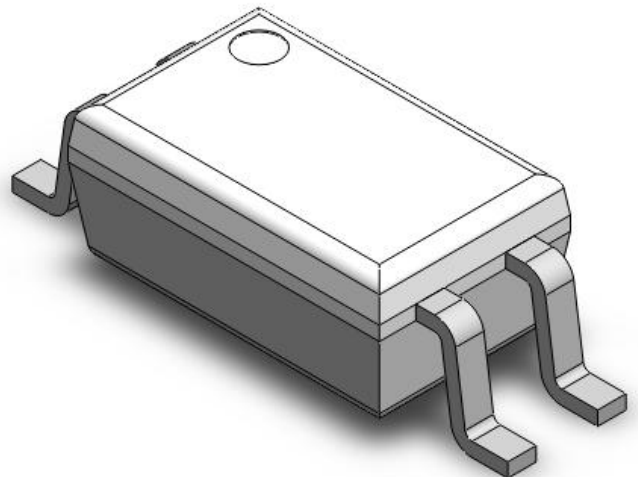
### SCHEMATIC



### PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

### PACKAGE OUTLINE



**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	VALUE	UNIT	NOTE
<b>INPUT</b>				
Forward Current	$I_F$	60	mA	
Peak Forward Current	$I_{FP}$	1	A	1
Reverse Voltage	$V_R$	6	V	
Input Power Dissipation	$P_I$	100	mW	
<b>OUTPUT</b>				
Collector - Emitter Voltage	$V_{CEO}$	80	V	
Emitter - Collector Voltage	$V_{ECO}$	7	V	
Collector Current	$I_C$	50	mA	
Output Power Dissipation	$P_O$	150	mW	
<b>COMMON</b>				
Total Power Dissipation	$P_{tot}$	200	mW	
Isolation Voltage	$V_{iso}$	3750	V <sub>rms</sub>	2
Operating Temperature	$T_{opr}$	-55~110	°C	
Storage Temperature	$T_{stg}$	-55~125	°C	
Soldering Temperature	$T_{sol}$	260	°C	

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%

#### ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

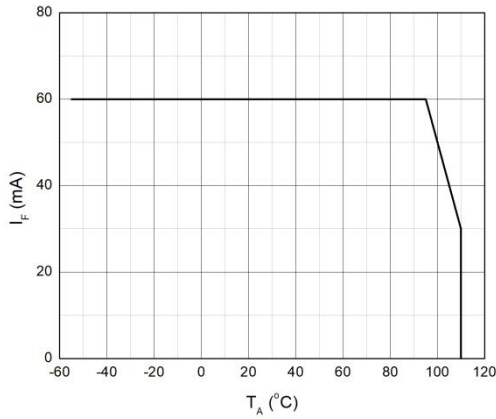
PARAMETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V <sub>F</sub>	-	-	1.4	V	IF=10mA	
Reverse Current	I <sub>R</sub>	-	-	10	μA	VR=6V	
Input Capacitance	C <sub>in</sub>	-	10	-	pF	V=0, f=1kHz	
OUTPUT							
Collector Dark Current	I <sub>CEO</sub>	-	-	100	nA	VCE=20V, IF=0	
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	80	-	-	V	IC=0.1mA, IF=0	
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	7	-	-	V	IE=0.1mA, IF=0	
TRANSFER CHARACTERISTICS							
Current Transfer Ratio	TWS3H7	CTR	50	-	600	%	IF=5mA, VCE=5V
	TWS3H7A		80	-	160		
	TWS3H7B		130	-	260		
	TWS3H7C		200	-	400		
	TWS3H7D		300	-	600		
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	-	0.1	0.2	V	IF=10mA, IC=1mA	
Isolation Resistance	R <sub>ISO</sub>	10 <sup>12</sup>	10 <sup>14</sup>	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C <sub>IO</sub>	-	0.4	1	pF	V=0, f=1MHz	
Response Time (Rise)	t <sub>r</sub>	-	3	18	μs	VCE=2V, IC=2mA	3
Response Time (Fall)	t <sub>f</sub>	-	4	18	μs	RL=100Ω	3
Cut-off Frequency	f <sub>c</sub>	-	80	-	kHz	VCE=2V, IC=2mA RL=100Ω,-3dB	4

Note 3. Fig.12&13

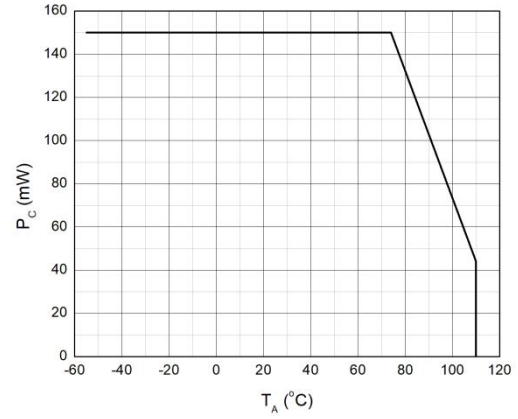
Note 4. Fig.14

#### CHARACTERISTIC CURVES

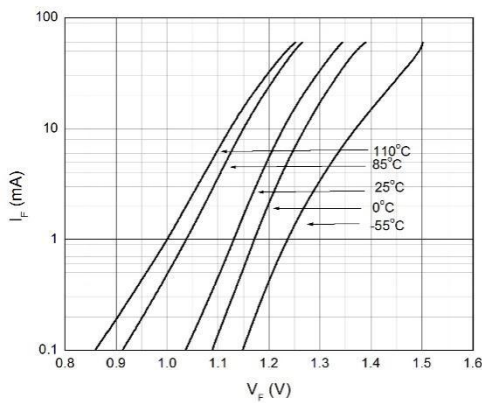
**Fig.1 Forward Current vs. Ambient Temperature**



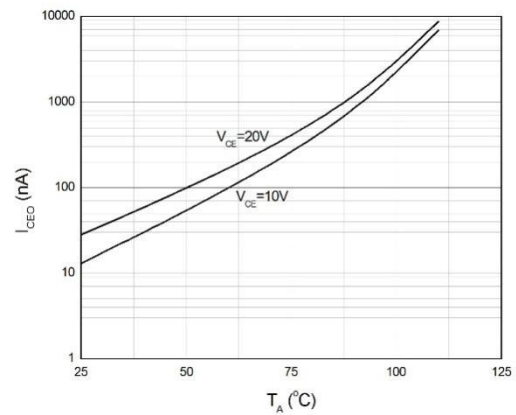
**Fig.2 Collector Power Dissipation vs. Ambient Temperature**



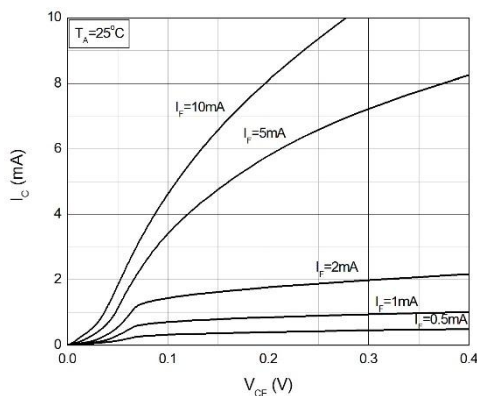
**Fig.3 Forward Current vs. Forward Voltage**



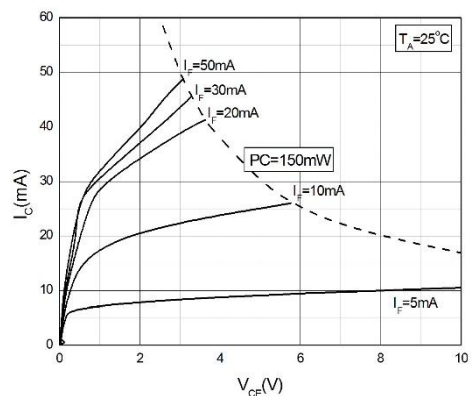
**Fig.4 Collector Dark Current vs. Ambient Temperature**



**Fig.5 Collector Current vs. Collector-emitter Voltage**

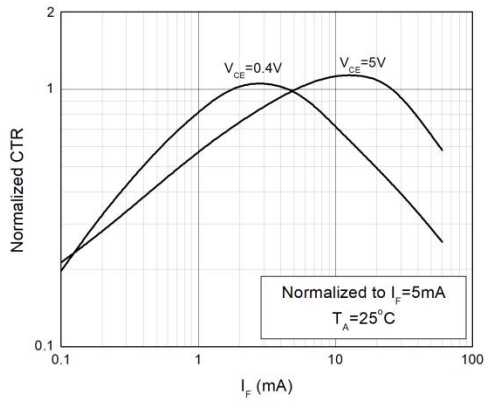


**Fig.6 Collector Current vs. Collector-emitter Voltage**

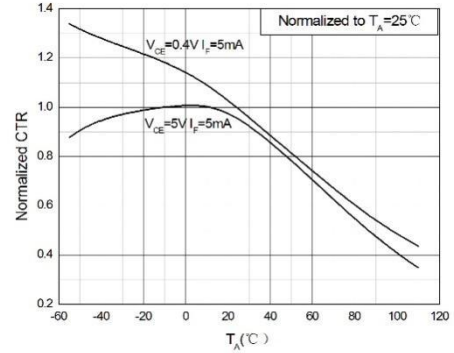


#### CHARACTERISTIC CURVES

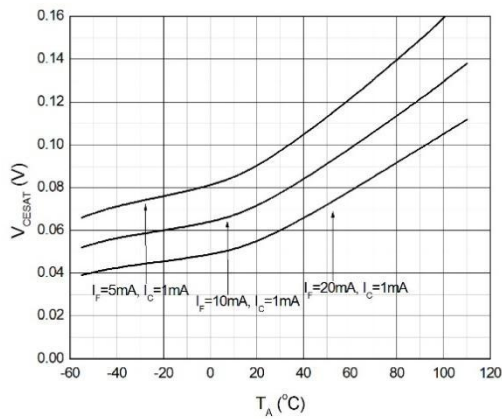
**Fig.7 Normalized Current Transfer Ratio vs. Forward Current**



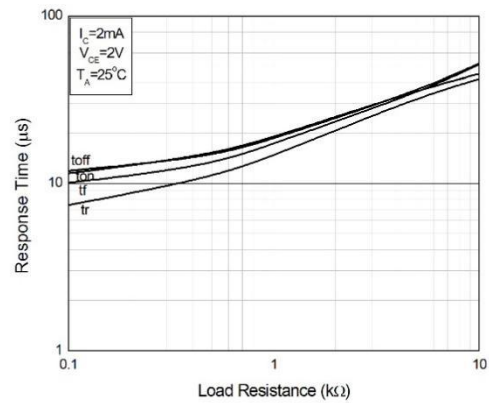
**Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature**



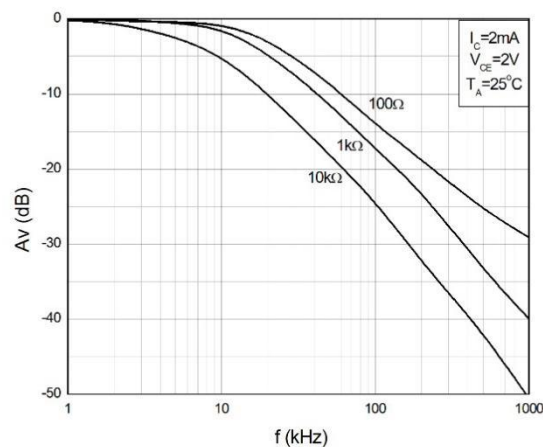
**Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature**



**Fig.10 Switching Time vs. Load Resistance**

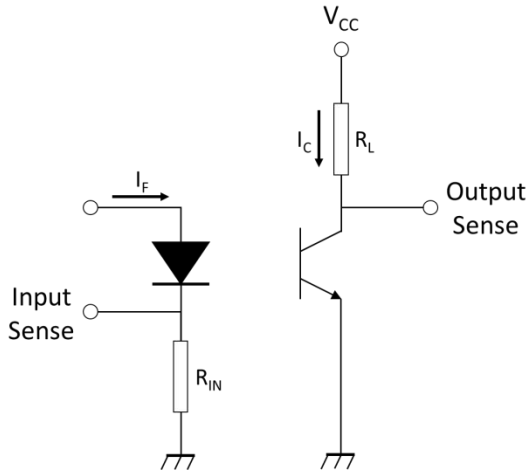


**Fig.11 Frequency Response**

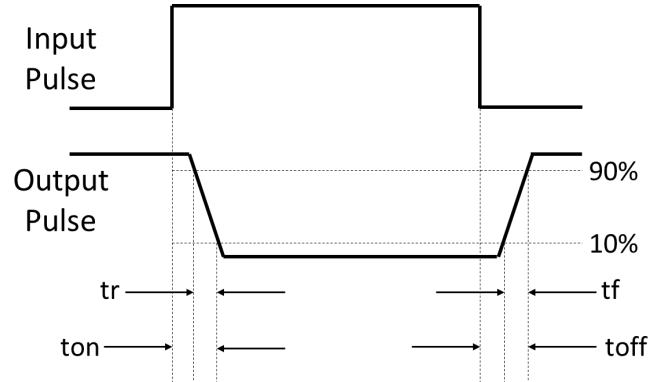


**TEST CIRCUITS**

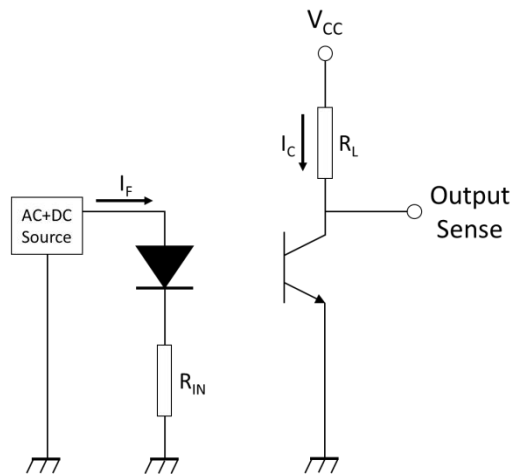
**Fig.12 Test Circuits of Response Time**



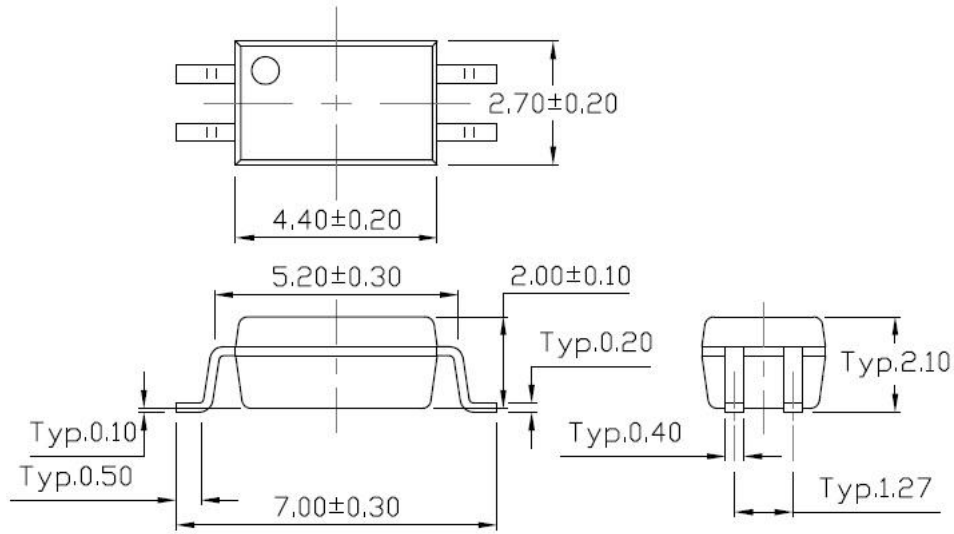
**Fig.13 Curves of Response Time**



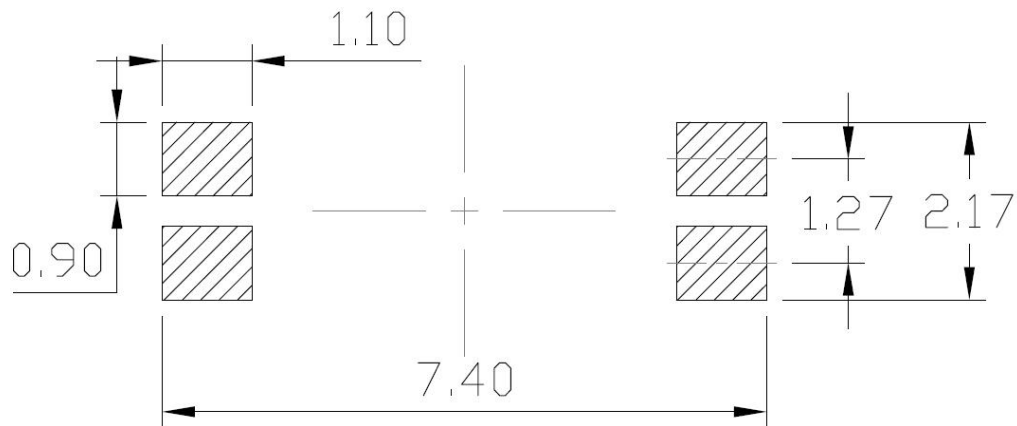
**Fig.14 Test Circuits of Frequency Response**



**PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)**

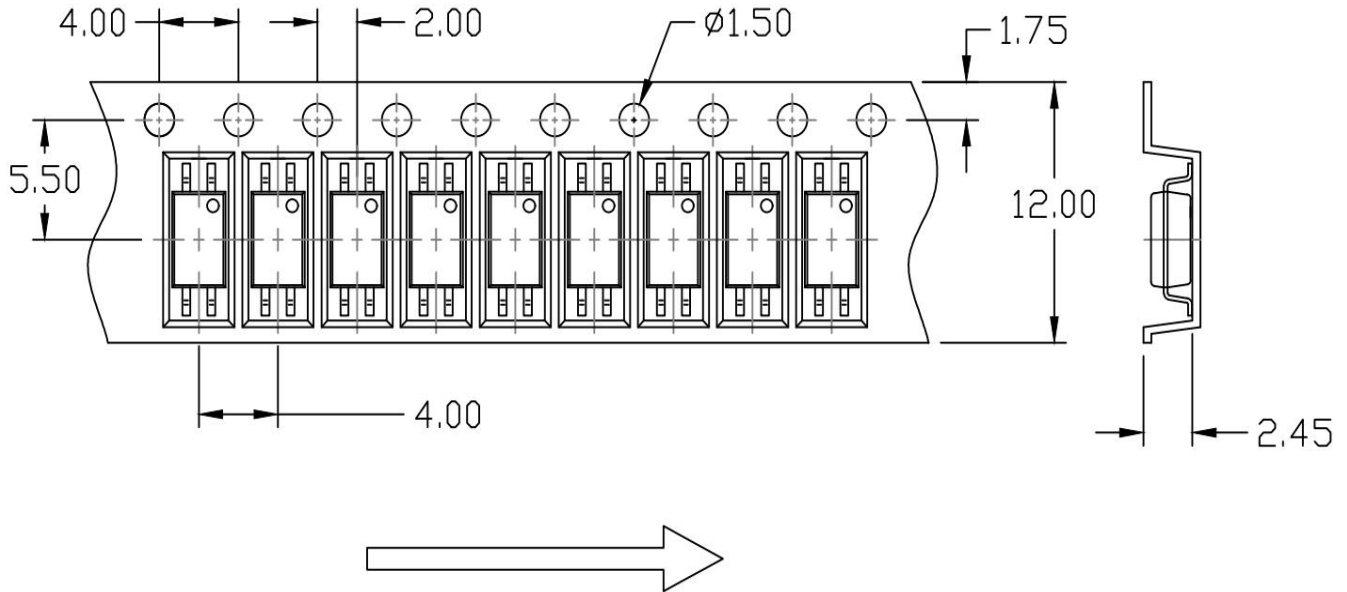


**Recommended Solder Mask (Dimensions in mm unless otherwise stated)**

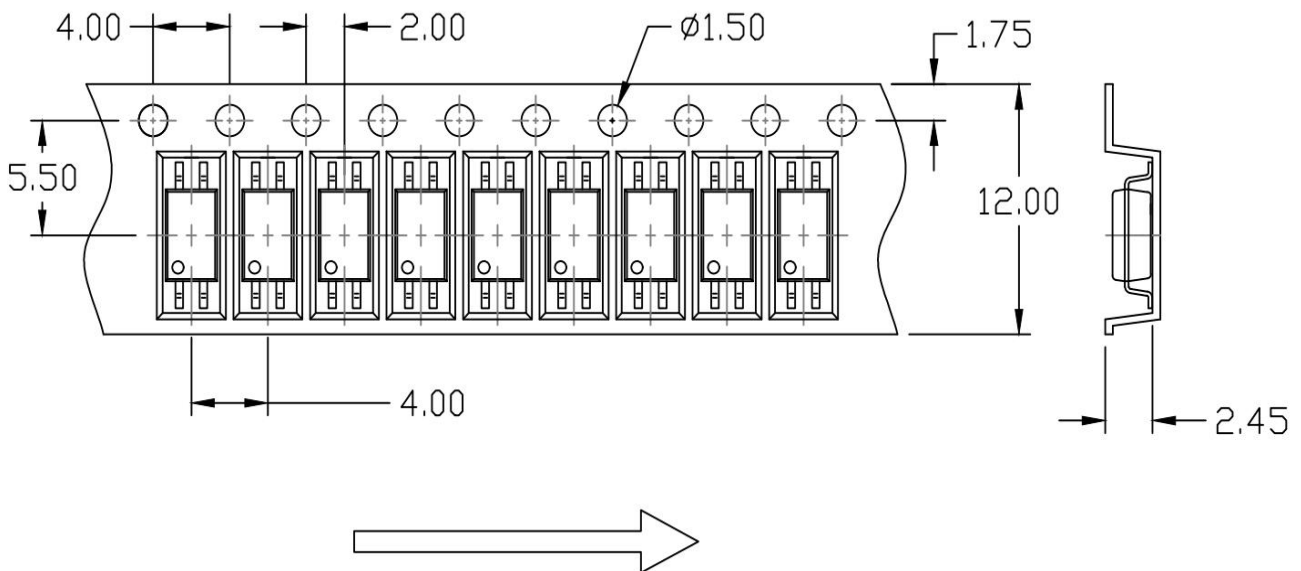


#### CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

##### Option T1



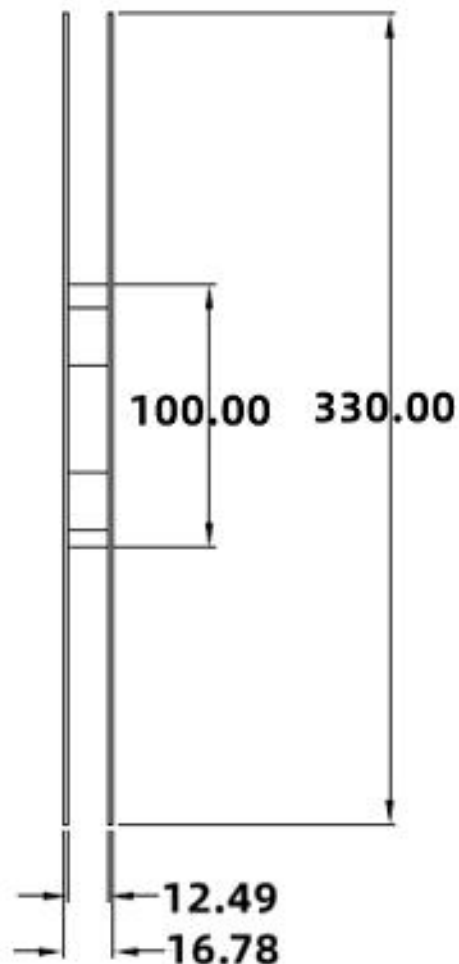
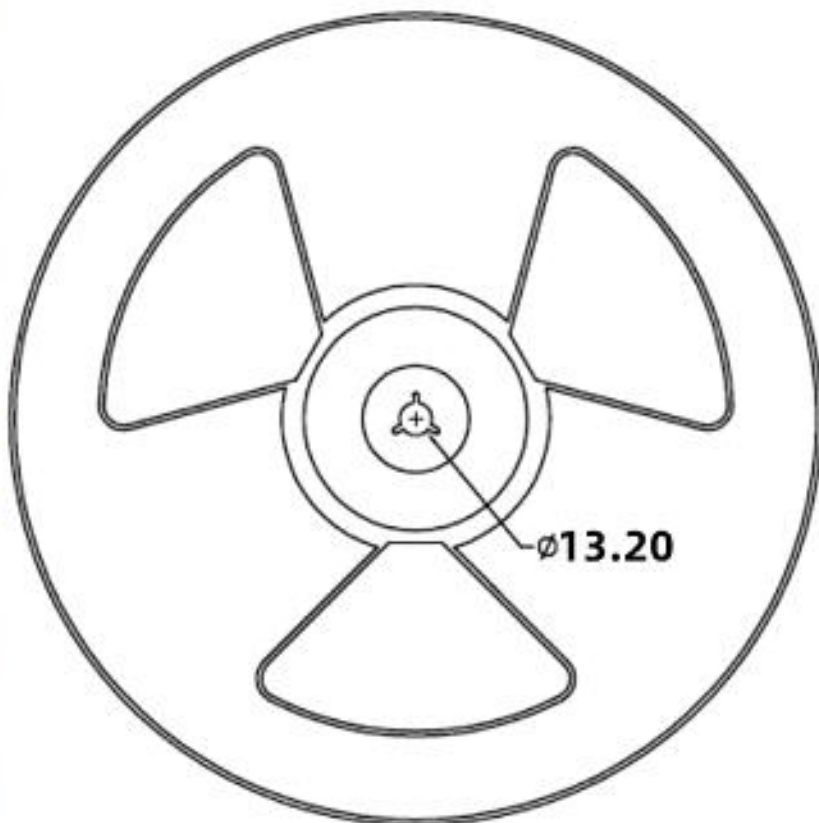
##### Option T2





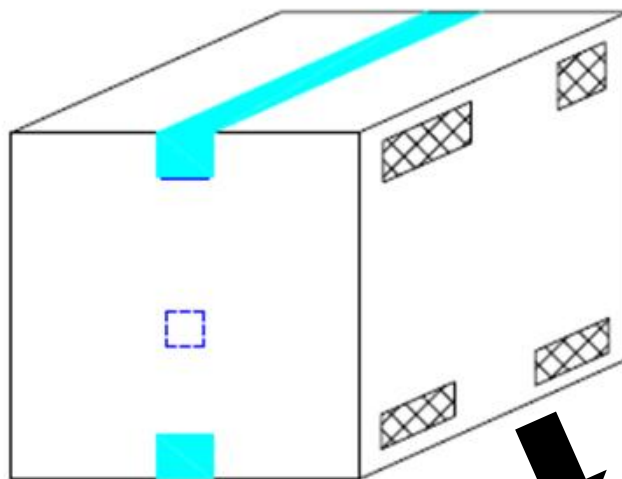
#### REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1 & T2

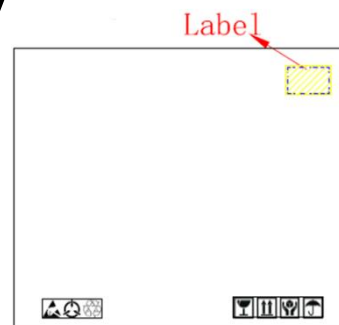


**BOX SPECIFICATIONS (Reel Type)****Inner Box**

- L x W x H = 36cm x 36cm x 6.9cm

**Outer Box**

- L x W x H = 45cm x 38cm x 38cm



#### ORDERING AND MARKING INFORMATION

##### MARKING INFORMATION



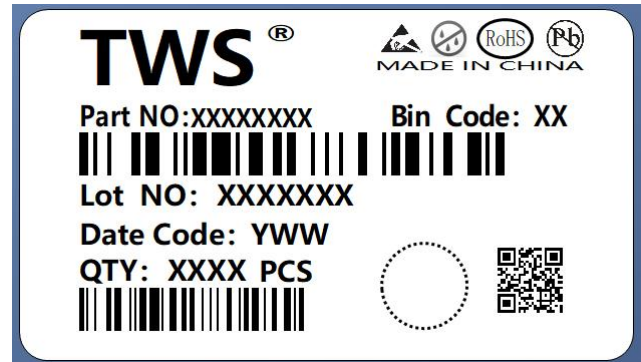
**TWS** : Company Abbr.  
**3H7** : Part Number  
**X** : CTR Rank  
**Y** : Fiscal Year  
**WW** : Work Week

##### ORDERING INFORMATION

**TWS3H7X(Z)-G**

TWS – Company Abbr.  
 3H7 – Part Number  
 X – Rank (A/B or None)  
 Z – Tape and Reel Option (T1/T2)  
 G – Green

##### LABEL INFORMATION

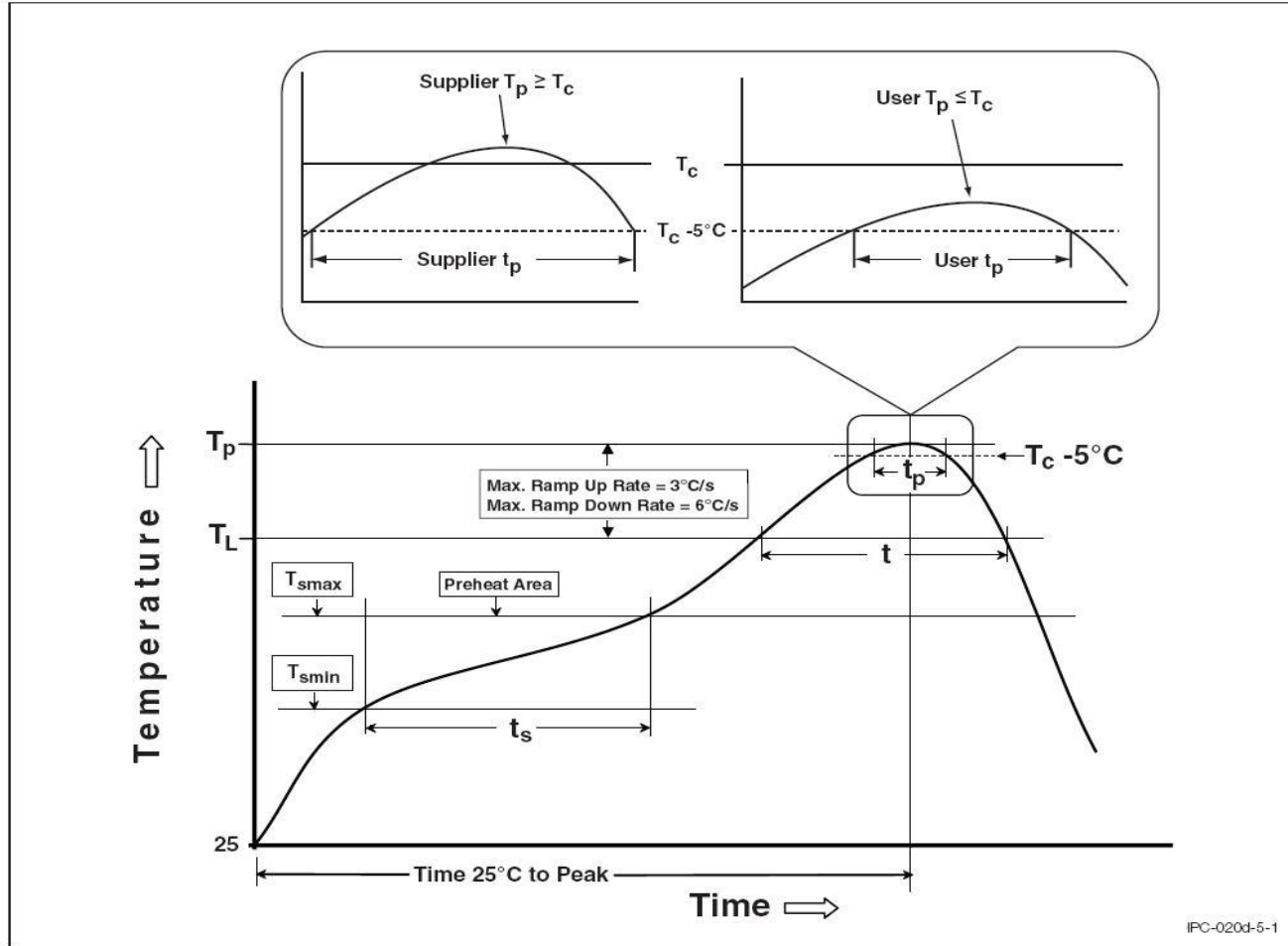


##### PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	5000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 75k Units
T2	5000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 75k Units

#### REFLOW INFORMATION

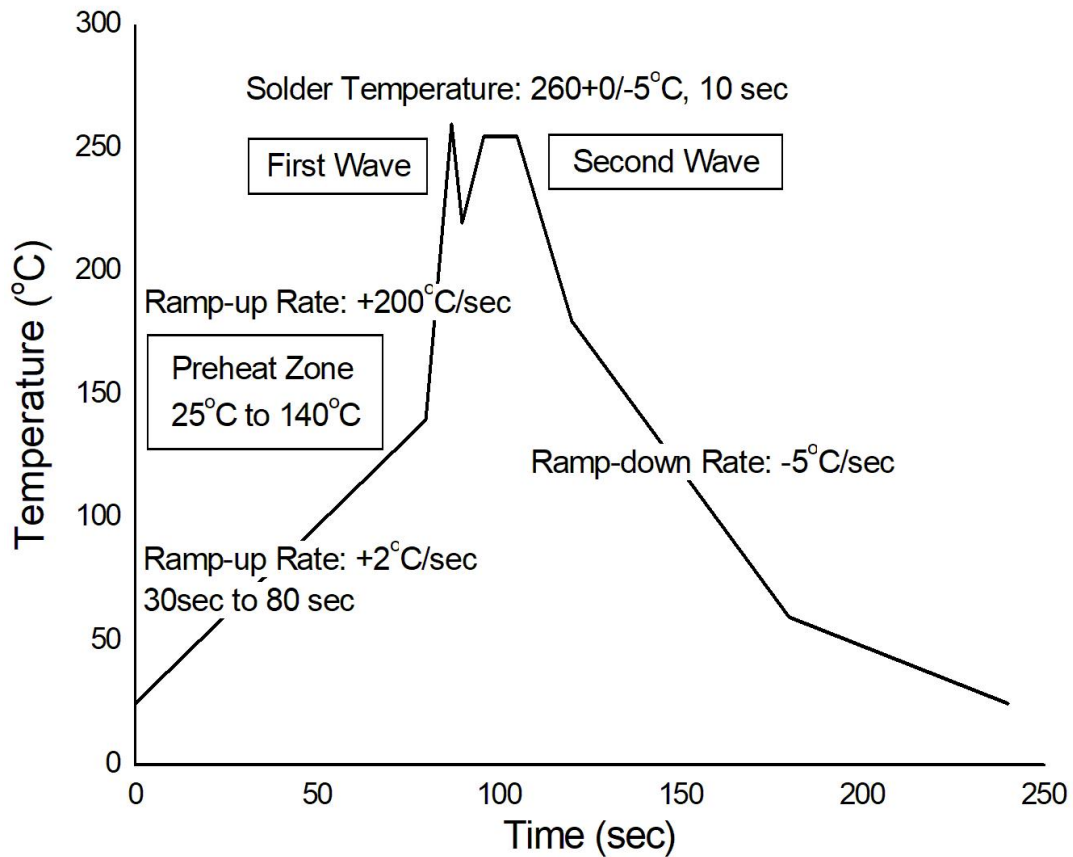
##### REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmmin)	100	150°C
Temperature Max. (Tsmmax)	150	200°C
Time (ts) from (Tsmmin to Tsmmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

**TEMPERATURE PROFILE OF SOLDERING**

**WAVE SOLDERING (JESD22-A111 COMPLIANT)**



**HAND SOLDERING BY SOLDERING IRON**

Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.